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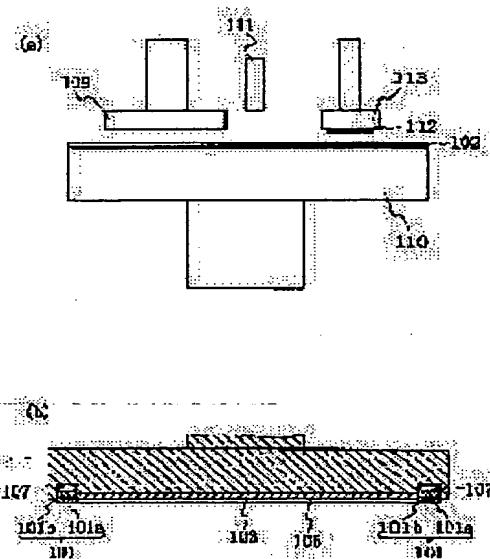
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(54) POLISHING DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To restrain the occurrence of polishing quantity abnormality in a substrate outer peripheral part by arranging the ring-shaped resin part formed on the surface contacting with a polishing pad of a retainer ring and a ring-shaped holding member composed of a material being fixedly arranged on the resin part and having mechanical strength higher than the resin part.

SOLUTION: A retainer ring 101 is formed as a two-piece structure of the resin part 101a and the metallic part 101b, so that the retainer ring 101 is remarkably improved in mechanical strength. While, in the retainer ring 101, the resin part 101a only contacts with a polishing pad 102, but the metallic part 101b does not contact with it. Therefore, a metallic component expands to the polishing pad 102, adverse influence is not exerted on a characteristic of a device formed on a substrate 105, and even if a polishing processing quantity increases, polishing abnormality caused in the substrate outer peripheral part of a polishing object can be restrained.



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